



M T B F

(EIAJ RCR-9102B)

Model	G1W-12
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No.	Parts	Q'ty of Device	Failure rate [$10^{-6}/H$]	Reference
1	IC	Linear	4	0.0960
2	Transistors	NPN/PNP	0	0.0000
3	Transistors	Power NPN/PNP	2	0.0840
4	FET	MOS FET	2	0.1980
5	Diodes	FR	4	0.0880
6	Diodes	Zener	2	0.0480
7	Diodes	bridge	4	0.2640
8	Resistors	Metal Film	32	0.5120
9	Resistors	Power Film	6	0.2460
10	Resistors	variable	2	0.0320
11	Capacitors	Aluminum Electrolytic	10	0.1900
12	Capacitors	Film	6	0.0504
13	Transformer	Power	1	0.3600
14	Fuses		3	0.0600
15	Connectors	Printed Circuit Board	8	0.4160
16	Connection	Hand Solder	11	0.0286
17	Connection	Flow Solder	286	0.1487
18	Connection	Crimp	32	0.0198
19	Connection	Screw	5	0.0050
20	Printed Circuit Board	Through Hole	2	0.0900
Total Failure Rate [$10^{-6}/H$]			2.9366	

M T B F	[H]	340,000
Ambient Temperature	[°C]	-
Load Factor	[%]	-